SiT8924B
Automotive AEC-Q100 Oscillator

SiTime

Features

- AEC-Q100 with extended temperature range (-55°C to 125°C)
- Frequencies between 1 MHz and 110 MHz accurate to 6 decimal places
- Supply voltage of 1.8V or 2.25V to 3.63V
- Excellent total frequency stability as low as ±20 ppm
- Industry best G-sensitivity of 0.1 PPB/G
- Low power consumption of 3.8 mA typical at 1.8V
- LVCMOS/LVTTL compatible output
- Industry-standard packages: 2.0 x 1.6, 2.5 x 2.0, 3.2 x 2.5, 5.0 x 3.2, 7.0 x 5.0 mm x mm
- RoHS and REACH compliant, Pb-free, Halogen-free and Antimony-free

Applications

- Automotive, extreme temperature and other high-rel electronics
- Infotainment systems, collision detection devices, and in-vehicle networking
- Powertrain control

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Electrical Characteristics

All Min and Max limits are specified over temperature and rated operating voltage with 15 pF output load unless otherwise stated. Typical values are at 25°C and nominal supply voltage.

Table 1. Electrical Characteristics

Parameters	Symbol	Min.	Typ.	Max.	Unit	Condition
Frequency Range						
Output Frequency Range	f	1	–	110	MHz	Refer to Table 13 and Table 14 for a list supported frequencies
Frequency Stability and Aging						
Frequency Stability	F_stab	-20	–	+20	ppm	Inclusive of Initial tolerance at 25°C, 1st year aging at 25°C, and variations over operating temperature, rated power supply voltage and load (15 pF ± 10%).
		-25	–	+25	ppm	
		-30	–	+30	ppm	
		-50	–	+50	ppm	
Operating Temperature Range						
Operating Temperature Range (ambient)	T_use	-40	–	+85	°C	Industrial, AEC-Q100 Grade 3
		-40	–	+105	°C	Extended Industrial, AEC-Q100 Grade 2
		-40	–	+125	°C	Automotive, AEC-Q100 Grade 1
		-55	–	+125	°C	Extended Temperature, AEC-Q100
Supply Voltage and Current Consumption						
Supply Voltage	Vdd	1.62	1.8	1.98	V	All voltages between 2.25V and 3.63V including 2.5V, 2.8V, 3.0V and 3.3V are supported.
		2.25	–	3.63	V	
Current Consumption	Idd	–	4.0	4.8	mA	No load condition, f = 20 MHz, Vdd = 2.25V to 3.63V
		–	3.8	4.5	mA	No load condition, f = 20 MHz, Vdd = 1.8V
LVCMOS Output Characteristics						
Duty Cycle	DC	45	–	55	%	All Vdds
Rise/Fall Time	Tr, Tf	–	1.5	3	ns	Vdd = 2.25V - 3.63V, 20% - 80%
		–	1.3	2.5	ns	Vdd = 1.8V, 20% - 80%
Output High Voltage	VOH	90%	–	–	Vdd	IOH = -4 mA (Vdd = 3.0V or 3.3V) IOH = -3 mA (Vdd = 2.8V and Vdd = 2.5V) IOH = -2 mA (Vdd = 1.8V)
Output Low Voltage	VOL	–	–	10%	Vdd	IOL = 4 mA (Vdd = 3.0V or 3.3V) IOL = 3 mA (Vdd = 2.8V and Vdd = 2.5V) IOL = 2 mA (Vdd = 1.8V)
Input Characteristics						
Input High Voltage	VIH	70%	–	–	Vdd	Pin 1, OE
Input Low Voltage	VIL	–	–	30%	Vdd	Pin 1, OE
Input Pull-up Impedence	Z_in	–	100	–	kΩ	Pin 1, OE logic high or logic low
Startup and Resume Timing						
Startup Time	T_start	–	–	10	ms	Measured from the time Vdd reaches its rated minimum value
Enable/Disable Time	T_oe	–	–	130	ns	f = 110 MHz. For other frequencies, T_oe = 100 ns + 3 * cycles
Jitter						
RMS Period Jitter	T_jitt	–	1.6	2.5	ps	f = 75 MHz, 2.25V to 3.63V
		–	1.9	3.0	ps	f = 75 MHz, 1.8V
RMS Phase Jitter (random)	T_phj	–	0.5	–	ps	f = 75 MHz, Integration bandwidth = 900 kHz to 7.5 MHz
		–	1.3	–	ps	f = 75 MHz, Integration bandwidth = 12 kHz to 20 MHz

Table 2. Pin Description

Pin	Symbol		Functionality
1	Output Enable	Output Enable	H[1]: specified frequency output L: output is high impedance. Only output driver is disabled.
	No Connect	No Connect	Any voltage between 0 and Vdd or Open[1]: Specified frequency output. Pin 1 has no function.
2	GND	Power	Electrical ground[2]
3	OUT	Output	Oscillator output
4	VDD	Power	Power supply voltage[2]

Top View

OE/NC 1 — 4 VDD

GND 2 — 3 OUT

Figure 1. Pin Assignments

Notes:

1. In OE mode, a pull-up resistor of 10k option is recommended if pin 1 is left floating.

2. A capacitor of value 0.1 µF or higher between Vdd and GND is required.

Table 3. Absolute Maximum Limits

Attempted operation outside the absolute maximum ratings may cause permanent damage to the part. Actual performance of the IC is only guaranteed within the operational specifications, not at absolute maximum ratings.

Parameter	Min.	Max.	Unit
Storage Temperature	-65	150	°C
Vdd	-0.5	4	V
Electrostatic Discharge	–	2000	V
Soldering Temperature (follow standard Pb free soldering guidelines)	–	260	°C
Junction Temperature[3]	–	150	°C

Note:

3. Exceeding this temperature for extended period of time may damage the device.

Table 4. Thermal Consideration[4]

Package	θJA, 4 Layer Board (°C/W)	θJA, 2 Layer Board (°C/W)	θJC, Bottom (°C/W)
7050	142	273	30
5032	97	199	24
3225	109	212	27
2520	117	222	26
2016	152	252	36

Note:

4. Refer to JESD51 for θJA and θJC definitions, and reference layout used to determine the θJA and θJC values in the above table.

Table 5. Maximum Operating Junction Temperature[5]

| Max Operating Temperature (ambient)	Maximum Operating Junction Temperature
85°C	95°C
105°C	115°C
125°C	135°C

Note:

5. Datasheet specifications are not guaranteed if junction temperature exceeds the maximum operating junction temperature.
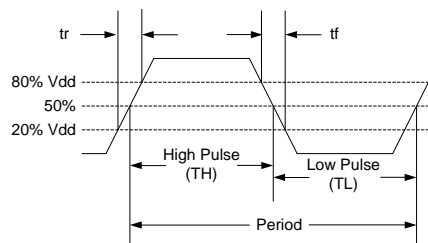
Table 6. Environmental Compliance

Parameter	Condition/Test Method
Mechanical Shock	MIL-STD-883F, Method 2002
Mechanical Vibration	MIL-STD-883F, Method 2007
Temperature Cycle	JESD22, Method A104
Solderability	MIL-STD-883F, Method 2003
Moisture Sensitivity Level	MSL1 @ 260°C

Test Circuit and Waveform[6]
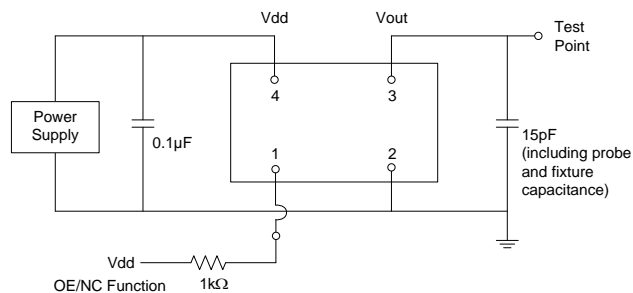
Figure 2. Test Circuit
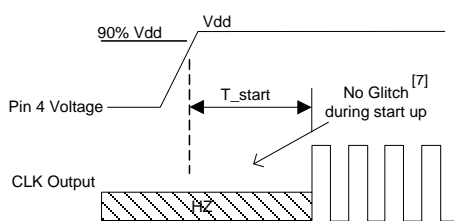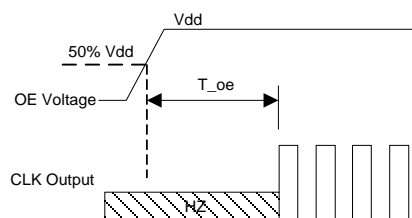

Figure 3. Waveform

Note:

6. Duty Cycle is computed as Duty Cycle = TH/Period.

Timing Diagrams

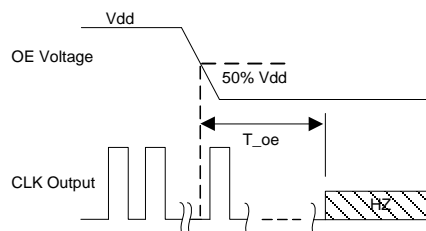
T_start: Time to start from power-off

Figure 4. Startup Timing (OE Mode)

T_oe: Time to re-enable the clock output

Figure 5. OE Enable Timing (OE Mode Only)

T_oe: Time to put the output in High Z mode

Figure 6. OE Disable Timing (OE Mode Only)

Note:

7. SiT8924 has "no runt" pulses and "no glitch" output during startup or resume.

Performance Plots[8]
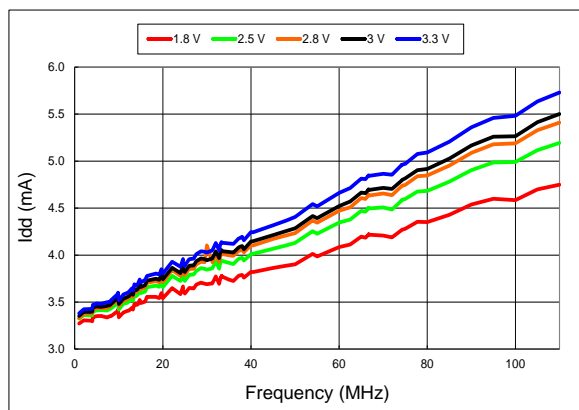
Figure 7. Idd vs Frequency
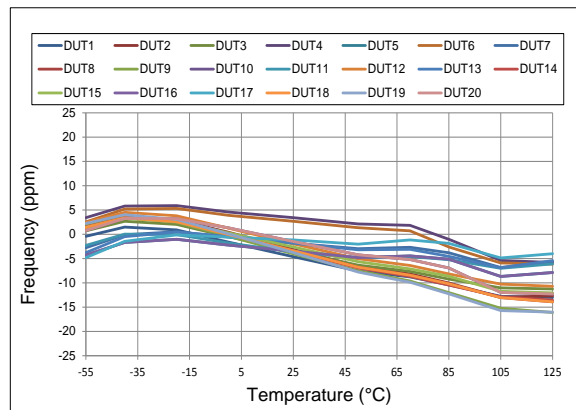
Figure 8. Frequency vs Temperature
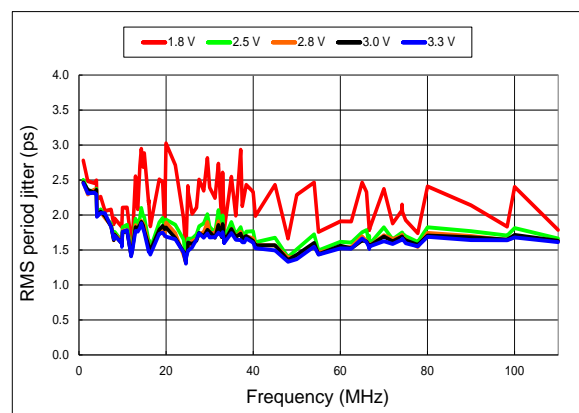
Figure 9. RMS Period Jitter vs Frequency
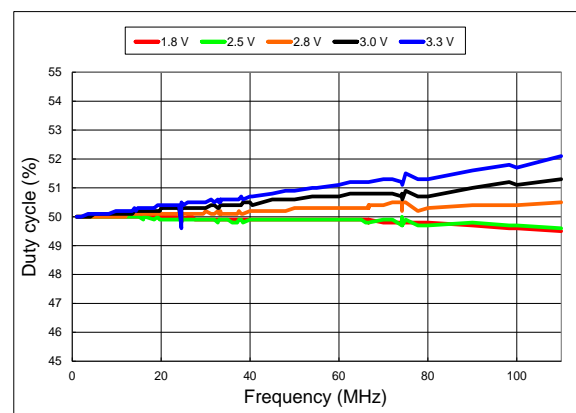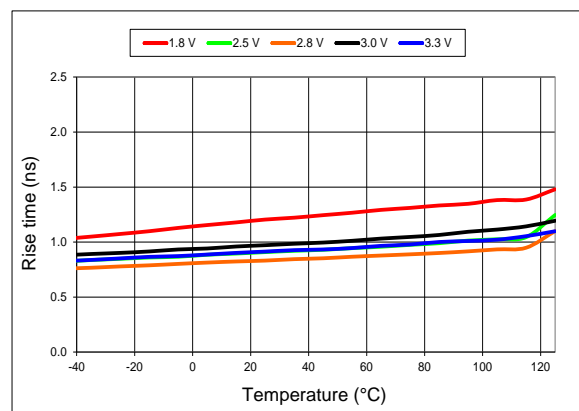

Figure 10. Duty Cycle vs Frequency

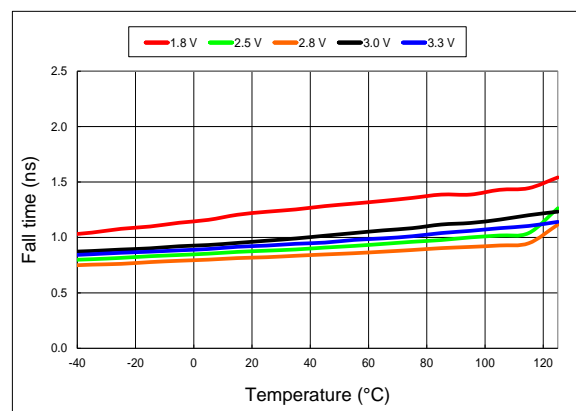**Figure 11. 20%-80% Rise Time vs Temperature**

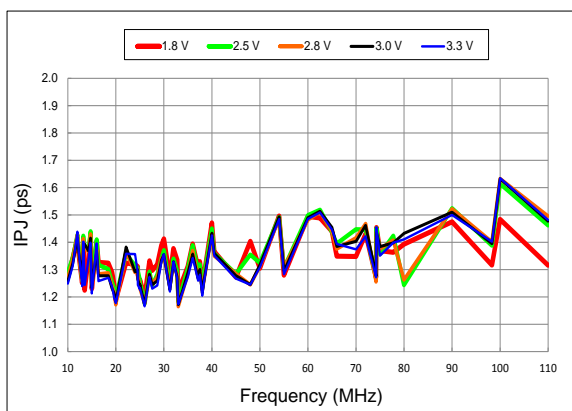

Figure 12. 20%-80% Fall Time vs Temperature

Performance Plots[8]

Figure 13. RMS Integrated Phase Jitter Random (12 kHz to 20 MHz) vs Frequency[9]
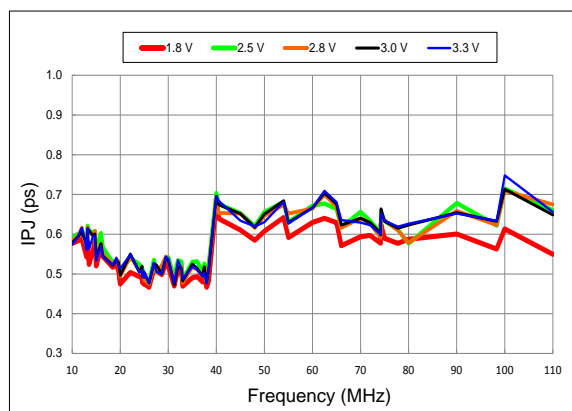

Figure 14. RMS Integrated Phase Jitter Random (900 kHz to 20 MHz) vs Frequency[9]

Notes:

8. All plots are measured with 15 pF load at room temperature, unless otherwise stated.

9. Phase noise plots are measured with Agilent E5052B signal source analyzer. Integration range is up to 5 MHz for carrier frequencies up to 40 MHz.

Programmable Drive Strength

The SiT8924 includes a programmable drive strength feature to provide a simple, flexible tool to optimize the clock rise/fall time for specific applications. Benefits from the programmable drive strength feature are:

- Improves system radiated electromagnetic interference (EMI) by slowing down the clock rise/fall time.

- Improves the downstream clock receiver's (RX) jitter by decreasing (speeding up) the clock rise/fall time.

- Ability to drive large capacitive loads while maintaining full swing with sharp edge rates.

For more detailed information about rise/fall time control and drive strength selection, see the SiTime Application Notes section: http://www.sitime.com/support/application-notes.

EMI Reduction by Slowing Rise/Fall Time

Figure 15 shows the harmonic power reduction as the rise/fall times are increased (slowed down). The rise/fall times are expressed as a ratio of the clock period. For the ratio of 0.05, the signal is very close to a square wave. For the ratio of 0.45, the rise/fall times are very close to near-triangular waveform. These results, for example, show that the 11th clock harmonic can be reduced by 35 dB if the rise/fall edge is increased from 5% of the period to 45% of the period.
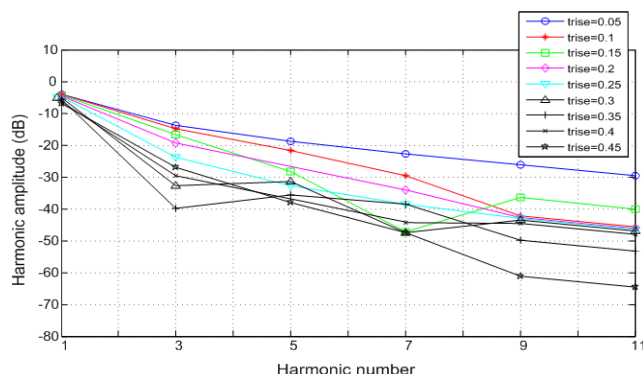

Figure 15. Harmonic EMI reduction as a Function of Slower Rise/Fall Time

Jitter Reduction with Faster Rise/Fall Time

Power supply noise can be a source of jitter for the downstream chipset. One way to reduce this jitter is to speed up the rise/fall time of the input clock. Some chipsets may also require faster rise/fall time in order to reduce their sensitivity to this type of jitter. Refer to the Rise/Fall Time Tables (Table 7 to Table 11) to determine the proper drive strength.

High Output Load Capability

The rise/fall time of the input clock varies as a function of the actual capacitive load the clock drives. At any given drive strength, the rise/fall time becomes slower as the output load increases. As an example, for a 3.3V SiT8924 device with default drive strength setting, the typical rise/fall time is 1ns for 15 pF output load. The typical rise/fall time slows down to 2.6 ns when the output load increases to 45 pF.

One can choose to speed up the rise/fall time to 1.83 ns by then increasing the drive strength setting on the SiT8924.

The SiT8924 can support up to 60 pF in maximum capacitive loads with drive strength settings. Refer to the Rise/Tall Time Tables (Table 7 to 11) to determine the proper drive strength for the desired combination of output load vs. rise/fall time.

SiT8924 Drive Strength Selection

Tables 7 through 11 define the rise/fall time for a given capacitive load and supply voltage.

1. Select the table that matches the SiT8924 nominal supply voltage (1.8V, 2.5V, 2.8V, 3.0V, 3.3V).

2. Select the capacitive load column that matches the application requirement (5 pF to 60 pF)

3. Under the capacitive load column, select the desired rise/fall times.

4. The left-most column represents the part number code for the corresponding drive strength.

5. Add the drive strength code to the part number for ordering purposes.

Calculating Maximum Frequency

Based on the rise and fall time data given in Tables 7 through 11, the maximum frequency the oscillator can operate with guaranteed full swing of the output voltage over temperature can be calculated as follows:

$$\text{Max Frequency} = \frac{1}{5 \times \text{Trf\_20/80}}$$

where Trf_20/80 is the typical value for 20%-80% rise/fall time.

Example 1

Calculate f_{MAX} for the following condition:

- Vdd = 1.8V (Table 7)

- Capacitive Load: 30 pF

- Desired Tr/f time = 3 ns (rise/fall time part number code = E)

Part number for the above example:

SiT8924BI**E**12-18E-66.666660

↑

Drive strength code is inserted here. Default setting is "-"

Rise/Fall Time (20% to 80%) vs C$_{LOAD}$ Tables

Table 7. Vdd = 1.8V Rise/Fall Times for Specific C$_{LOAD}$

Rise/Fall Time Typ (ns)					
Drive Strength \ C$_{LOAD}$	5 pF	15 pF	30 pF	45 pF	60 pF
L	6.16	11.61	22.00	31.27	39.91
A	3.19	6.35	11.00	16.01	21.52
R	2.11	4.31	7.65	10.77	14.47
B	1.65	3.23	5.79	8.18	11.08
T	0.93	1.91	3.32	4.66	6.48
E	0.78	1.66	2.94	4.09	5.74
U	0.70	1.48	2.64	3.68	5.09
F or "-": default	0.65	1.30	2.40	3.35	4.56

Table 8. Vdd = 2.5V Rise/Fall Times for Specific C$_{LOAD}$

Rise/Fall Time Typ (ns)					
Drive Strength \ C$_{LOAD}$	5 pF	15 pF	30 pF	45 pF	60 pF
L	4.13	8.25	12.82	21.45	27.79
A	2.11	4.27	7.64	11.20	14.49
R	1.45	2.81	5.16	7.65	9.88
B	1.09	2.20	3.88	5.86	7.57
T	0.62	1.28	2.27	3.51	4.45
E or "-": default	0.54	1.00	2.01	3.10	4.01
U	0.43	0.96	1.81	2.79	3.65
F	0.34	0.88	1.64	2.54	3.32

Table 9. Vdd = 2.8V Rise/Fall Times for Specific C$_{LOAD}$

Rise/Fall Time Typ (ns)					
Drive Strength \ C$_{LOAD}$	5 pF	15 pF	30 pF	45 pF	60 pF
L	3.77	7.54	12.28	19.57	25.27
A	1.94	3.90	7.03	10.24	13.34
R	1.29	2.57	4.72	7.01	9.06
B	0.97	2.00	3.54	5.43	6.93
T	0.55	1.12	2.08	3.22	4.08
E or "-": default	0.44	1.00	1.83	2.82	3.67
U	0.34	0.88	1.64	2.52	3.30
F	0.29	0.81	1.48	2.29	2.99

Table 10. Vdd = 3.0V Rise/Fall Times for Specific C$_{LOAD}$

Rise/Fall Time Typ (ns)					
Drive Strength \ C$_{LOAD}$	5 pF	15 pF	30 pF	45 pF	60 pF
L	3.60	7.21	11.97	18.74	24.30
A	1.84	3.71	6.72	9.86	12.68
R	1.22	2.46	4.54	6.76	8.62
B	0.89	1.92	3.39	5.20	6.64
T or "-": default	0.51	1.00	1.97	3.07	3.90
E	0.38	0.92	1.72	2.71	3.51
U	0.30	0.83	1.55	2.40	3.13
F	0.27	0.76	1.39	2.16	2.85

Table 11. Vdd = 3.3V Rise/Fall Times for Specific C$_{LOAD}$

Rise/Fall Time Typ (ns)					
Drive Strength \	5 pF	15 pF	30 pF	45 pF	60 pF
L	3.39	6.88	11.63	17.56	23.59
A	1.74	3.50	6.38	8.98	12.19
R	1.16	2.33	4.29	6.04	8.34
B	0.81	1.82	3.22	4.52	6.33
T or "-": default	0.46	1.00	1.86	2.60	3.84
E	0.33	0.87	1.64	2.30	3.35
U	0.28	0.79	1.46	2.05	2.93
F	0.25	0.72	1.31	1.83	2.61

Pin 1 Configuration Options (OE or NC)

Pin 1 of the SiT8924 can be factory-programmed to support two modes: Output Enable (OE) or No Connect (NC).

Output Enable (OE) Mode

In the OE mode, applying logic low to the OE pin only disables the output driver and puts it in Hi-Z mode. The core of the device continues to operate normally. Power consumption is reduced due to the inactivity of the output. When the OE pin is pulled High, the output is typically enabled in <1µs.

No Connect (NC) Mode

In the NC mode, the device always operates in its normal mode and output the specified frequency regardless of the logic level on pin 1.

Table 12 below summarizes the key relevant parameters in the operation of the device in OE or NC mode.

Table 12. OE vs. NC

	OE	NC
Active current 20 MHz (max, 1.8V)	4.5 mA	4.5 mA
OE disable current (max. 1.8V)	3.8 mA	N/A
OE enable time at 110 MHz (max)	130 ns	N/A
Output driver in OE disable	High Z	N/A

Output on Startup and OE Enable

The SiT8924 comes with gated output. Its clock output is accurate to the rated frequency stability within the first pulse from initial device startup or when the output driver is enabled.

In addition, the SiT8924 supports "no runt" pulses and "no glitch" output during startup or when the device output driver is enabled as shown in the waveform captures in Figure 16 and Figure 17.

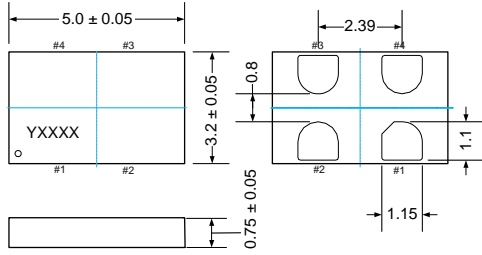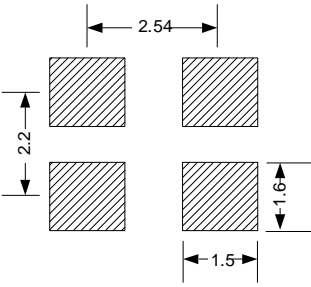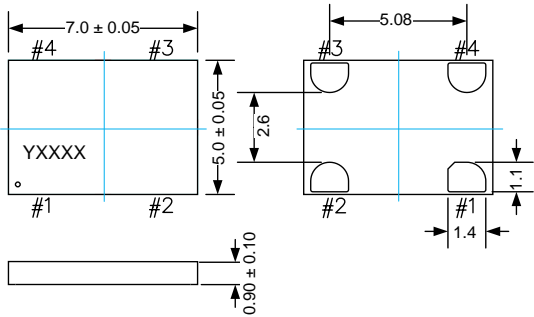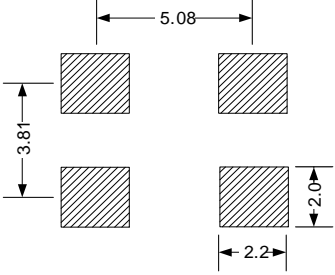

Figure 16. Startup Waveform vs. Vdd
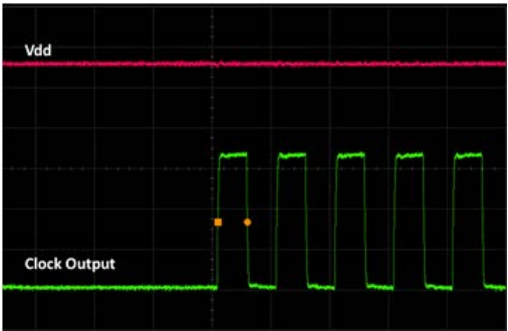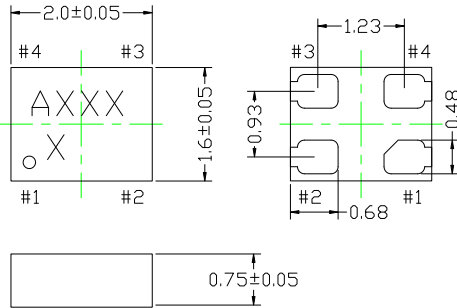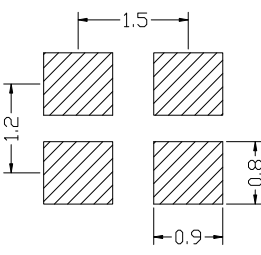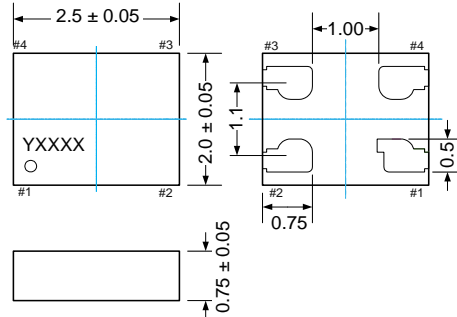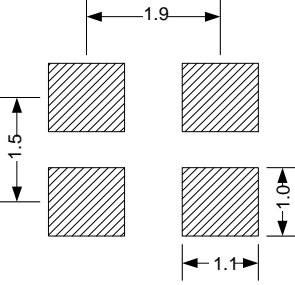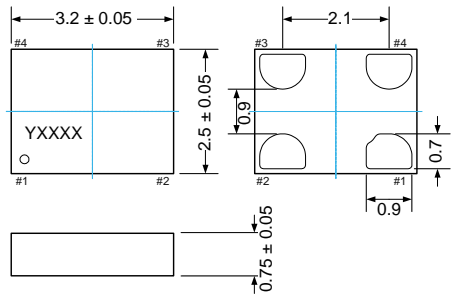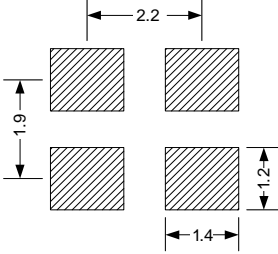
**Figure 17. Startup Waveform vs. Vdd
(Zoomed-in View of Figure 16)**

Dimensions and Patterns

Package Size – Dimensions (Unit: mm)[10]	Recommended Land Pattern (Unit: mm)[11]
2.0 x 1.6 x 0.75 mm	
2.5 x 2.0 x 0.75 mm	
3.2 x 2.5 x 0.75 mm	
5.0 x 3.2 x 0.75 mm	

Dimensions and Patterns

Package Size – Dimensions (Unit: mm)[10]	Recommended Land Pattern (Unit: mm)[11]

7.0 x 5.0 x 0.90 mm

Notes:

10. Top marking: Y denotes manufacturing origin and XXXX denotes manufacturing lot number. The value of "Y" will depend on the assembly location of the device.

11. A capacitor of value 0.1 µF or higher between Vdd and GND is required.

Ordering Information

The Part No. Guide is for reference only. To customize and build an exact part number, use the SiTime Part Number Generator.

SiT8924BA-12-18E-66.666666D

Part Family
"SiT8924"

Revision Letter
"B" is the revision

Temperature Range
"I" Industrial -40ºC to 85ºC
"E" Ext. Industrial -40ºC to 105ºC
"A" Automotive -40ºC to 125ºC
"M" Automotive -55ºC to 125ºC

Output Drive Strength
"–" Default (datasheet limits)
See Tables 7 to 11 for rise/fall times

"L"	"T"
"A"	"E"
"R"	"U"
"B"	"F"

Package Size
"7" 2.0 x 1.6 mm
"1" 2.5 x 2.0 mm
"2" 3.2 x 2.5 mm
"3" 5.0 x 3.2 mm
"8" 7.0 x 5.0 mm

Packing Method
"T": 12 mm Tape & Reel, 3ku reel
"Y": 12 mm Tape & Reel, 1ku reel
"D": 8 mm Tape & Reel, 3ku reel
"E": 8 mm Tape & Reel, 1ku reel
 Blank for Bulk

Frequency
Refer to the Supported Frequencies Tables below

Feature Pin
"E" for Output Enable
"N" for No Connect

Supply Voltage[12]
"18" for 1.8V ±10%
"25" for 2.5V ±10%
"28" for 2.8V ±10%
"30" for 3.0V ±10%
"33" for 3.3V ±10%
"XX" for 2.5V -10% to 3.3V +10%

Frequency Stability
"1" for ±20 ppm
"2" for ±25 ppm
"8" for ±30 ppm
"3" for ±50 ppm

Note:

12. The voltage portion of the SiT8924 part number consists of two characters that denote the specific supply voltage of the device. The SiT8924 supports either 1.8V ±10% or any voltage between 2.25V and 3.62V. In the 1.8V mode, one can simply insert 18 in the part number. In the 2.5V to 3.3V mode, two digits such as 18, 25 or 33 can be used in the part number to reflect the desired voltage. Alternatively, "XX" can be used to indicate the entire operating voltage range from 2.25V to 3.63V.

Table 13. Supported Frequencies (-40°C to +85°C)[13]

Frequency Range	
Min.	**Max.**
1.000000 MHz	110.000000 MHz

Table 14. Supported Frequencies (-40°C to +105°C or -40°C to +125°C)[13, 14]

Frequency Range	
Min.	**Max.**
1.000000 MHz	61.222999 MHz
61.974001 MHz	69.795999 MHz
70.485001 MHz	79.062999 MHz
79.162001 MHz	81.427999 MHz
82.232001 MHz	91.833999 MHz
92.155001 MHz	94.248999 MHz
94.430001 MHz	94.874999 MHz
94.994001 MHz	97.713999 MHz
98.679001 MHz	110.000000 MHz

Table 15. Supported Frequencies (-55°C to +125°C)[13, 14]

Frequency Range	
Min.	**Max.**
1.000000 MHz	61.222999 MHz
61.974001 MHz	69.239999 MHz
70.827001 MHz	78.714999 MHz
79.561001 MHz	80.159999 MHz
80.174001 MHz	80.779999 MHz
82.632001 MHz	91.833999 MHz
95.474001 MHz	96.191999 MHz
96.209001 MHz	96.935999 MHz
99.158001 MHz	110.000000 MHz

Notes:

13. Any frequency within the min and max values in the above tables are supported with 6 decimal places of accuracy.

14. Please contact SiTime for frequencies that are not listed in the tables above.

Table 16. Ordering Codes for Supported Tape & Reel Packing Method

Device Size (mm x mm)	16 mm T&R (3ku)	16 mm T&R (1ku)	12 mm T&R (3ku)	12 mm T&R (1ku)	8 mm T&R (3ku)	8 mm T&R (1ku)
2.0 x 1.6	–	–	–	–	D	E
2.5 x 2.0	–	–	–	–	D	E
3.2 x 2.5	–	–	–	–	D	E
5.0 x 3.2	–	–	T	Y	–	–
7.0 x 5.0	T	Y	–	–	–	–

Table 17. Additional Information

Document	Description	Download Link
Time Machine II	MEMS oscillator programmer	http://www.sitime.com/support/time-machine-oscillator-programmer
Field Programmable Oscillators	Devices that can be programmable in the field by Time Machine II	http://www.sitime.com/products/field-programmable-oscillators
Manufacturing Notes	Tape & Reel dimension, reflow profile and other manufacturing related info	http://www.sitime.com/component/docman/doc_download/243-manufacturing-notes-for-sitime-oscillators
Qualification Reports	RoHS report, reliability reports, composition reports	http://www.sitime.com/support/quality-and-reliability
Performance Reports	Additional performance data such as phase noise, current consumption and jitter for selected frequencies	http://www.sitime.com/support/performance-measurement-report
Termination Techniques	Termination design recommendations	http://www.sitime.com/support/application-notes
Layout Techniques	Layout recommendations	http://www.sitime.com/support/application-notes

Table 18. Revision History

Revision	Release Date	Change Summary
0.1	05/19/2015	Final production release
1.3	03/18/2016	Added the industrial temperature "-40°C to ±85°C" option Added support for ±20 ppm frequency stability Added 12 and 16 mm T&R information to Table 16
1.5	12/14/2016	Changed Clock Generator to SOT23 Oscillator Updated logo and company address, other page layout changes

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Supplemental Information

The Supplemental Information section is not part of the datasheet and is for informational purposes only.

Silicon MEMS Outperforms Quartz

Best Reliability

Silicon is inherently more reliable than quartz. Unlike quartz suppliers, SiTime has in-house MEMS and analog CMOS expertise, which allows SiTime to develop the most reliable products. Figure 1 shows a comparison with quartz technology.

Why is EpiSeal™ MEMS Best in Class:

- SiTime's MEMS resonators are vacuum sealed using an advanced EpiSeal™ process, which eliminates foreign particles and improves long term aging and reliability
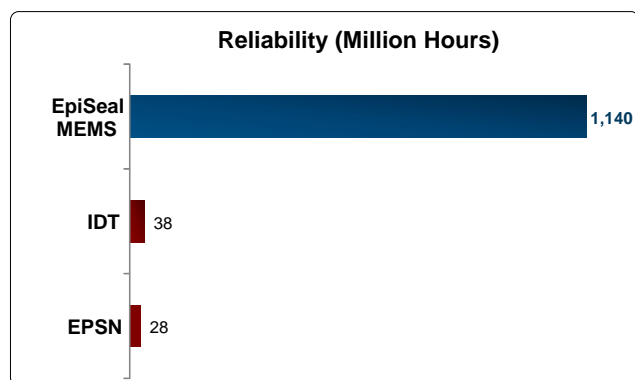- World-class MEMS and CMOS design expertise

Reliability (Million Hours)

EpiSeal MEMS	1,140
IDT	38
EPSN	28

Figure 1. Reliability Comparison[1]

Best Aging

Unlike quartz, MEMS oscillators have excellent long term aging performance which is why every new SiTime product specifies 10-year aging. A comparison is shown in Figure 2.

Why is EpiSeal MEMS Best in Class:

- SiTime's MEMS resonators are vacuum sealed using an advanced EpiSeal™ process, which eliminates foreign particles and improves long term aging and reliability
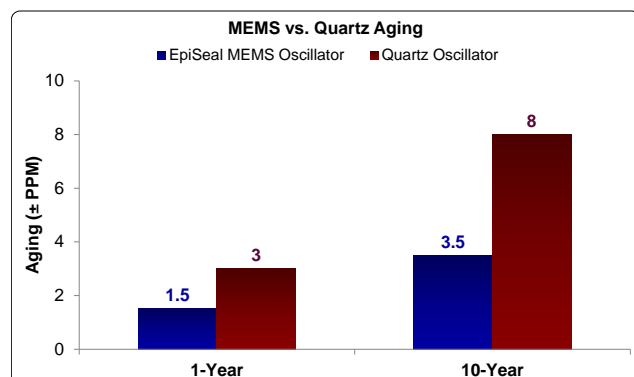- Inherently better immunity of electrostatically driven MEMS resonator

MEMS vs. Quartz Aging

■ EpiSeal MEMS Oscillator ■ Quartz Oscillator

1-Year: EpiSeal 1.5, Quartz 3
10-Year: EpiSeal 3.5, Quartz 8

Figure 2. Aging Comparison[2]

Best Electro Magnetic Susceptibility (EMS)

SiTime's oscillators in plastic packages are up to 54 times more immune to external electromagnetic fields than quartz oscillators as shown in Figure 3.

Why is EpiSeal MEMS Best in Class:

- Internal differential architecture for best common mode noise rejection
- Electrostatically driven MEMS resonator is more immune to EMS
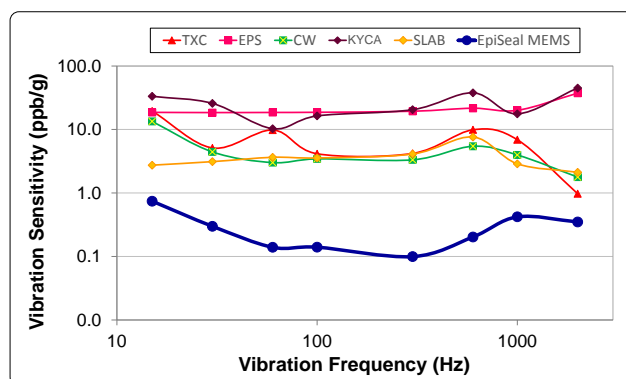
Figure 3. Electro Magnetic Susceptibility (EMS)[3]

Best Power Supply Noise Rejection

SiTime's MEMS oscillators are more resilient against noise on the power supply. A comparison is shown in Figure 4.

Why is EpiSeal MEMS Best in Class:

- On-chip regulators and internal differential architecture for common mode noise rejection
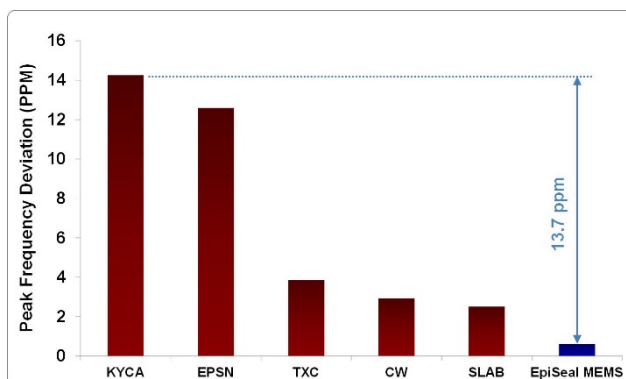- MEMS resonator is paired with advanced analog CMOS IC

Figure 4. Power Supply Noise Rejection[4]

Best Vibration Robustness

High-vibration environments are all around us. All electronics, from handheld devices to enterprise servers and storage systems are subject to vibration. Figure 5 shows a comparison of vibration robustness.

Why is EpiSeal MEMS Best in Class:

- The moving mass of SiTime's MEMS resonators is up to 3000 times smaller than quartz

- Center-anchored MEMS resonator is the most robust design

Figure 5. Vibration Robustness[5]

Figure labels:

- TXC = TXC
- Epson = EPSN
- Connor Winfield = CW
- Kyocera = KYCA
- SiLabs = SLAB
- SiTime = EpiSeal MEMS

Best Shock Robustness

SiTime's oscillators can withstand at least 50,000 *g* shock. They all maintain their electrical performance in operation during shock events. A comparison with quartz devices is shown in Figure 6.

Why is EpiSeal MEMS Best in Class:

- The moving mass of SiTime's MEMS resonators is up to 3000 times smaller than quartz

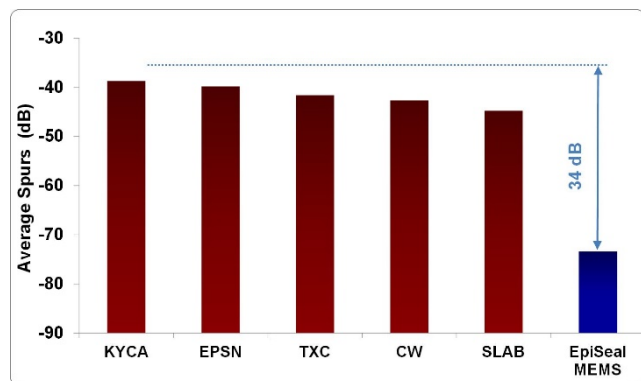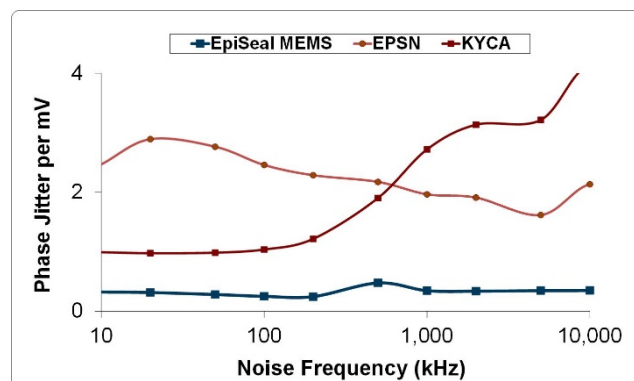- Center-anchored MEMS resonator is the most robust design

Figure 6. Shock Robustness[6]

Notes:

1. Data source: Reliability documents of named companies.
2. Data source: SiTime and quartz oscillator devices datasheets.
3. Test conditions for Electro Magnetic Susceptibility (EMS):
   - According to IEC EN61000-4.3 (Electromagnetic compatibility standard)
   - Field strength: 3V/m
   - Radiated signal modulation: AM 1 kHz at 80% depth
   - Carrier frequency scan: 80 MHz – 1 GHz in 1% steps
   - Antenna polarization: Vertical
   - DUT position: Center aligned to antenna

   Devices used in this test:

Label	Manufacturer	Part Number	Technology
EpiSeal MEMS	SiTime	SiT9120AC-1D2-33E156.250000	MEMS + PLL
EPSN	Epson	EG-2102CA156.2500M-PHPAL3	Quartz, SAW
TXC	TXC	BB-156.250MBE-T	Quartz, 3rd Overtone
CW	Conner Winfield	P123-156.25M	Quartz, 3rd Overtone
KYCA	AVX Kyocera	KC7050T156.250P30E00	Quartz, SAW
SLAB	SiLab	590AB-BDG	Quartz, 3rd Overtone + PLL

4. 50 mV pk-pk Sinusoidal voltage.

   Devices used in this test:

Label	Manufacturer	Part Number	Technology
EpiSeal MEMS	SiTime	SiT8208AI-33-33E-25.000000	MEMS + PLL
NDK	NDK	NZ2523SB-25.6M	Quartz
KYCA	AVX Kyocera	KC2016B25M0C1GE00	Quartz
EPSN	Epson	SG-310SCF-25M0-MB3	Quartz

5. Devices used in this test:
   same as EMS test stated in Note 3.
6. Test conditions for shock test:
   - MIL-STD-883F Method 2002
   - Condition A: half sine wave shock pulse, 500-g, 1ms
   - Continuous frequency measurement in 100 µs gate time for 10 seconds

   Devices used in this test:
   same as EMS test stated in Note 3.
7. Additional data, including setup and detailed results, is available upon request to qualified customer.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

SiTime:

SiT8924BE-12-XXE-10.000000E SIT8924BM-11-XXX-000.FP0000G SIT8924BM-11-XXX-000.FP0000D SIT8924BM-71-XXX-000.FP0000G SiT8924BE-12-18E-10.000000E SIT8924BM-11-XXX-000.FP0000E SIT8924BM-71-XXX-000.FP0000D SIT8924BM-71-XXX-000.FP0000E SIT8924BM-83-33E-8.000000X SIT8924BA-22-33E-8.192000G SIT8924BA-22-33E-20.000000G SIT8924BM-83-33E-40.000000X SiT8924BA-73-33E-30.000000E SiT8924BA-12-33E-60.000000E SiT8924BA-23-33E-5.644800E SiT8924BA-72-33E-27.000000E SiT8924BA-22-18E-55.466670E SiT8924BA-32-18E-12.000000Y SiT8924BM-12-33E-10.000000E SiT8924BA-23-33E-16.000000E SiT8924BE-73-XXE-27.000000E SiT8924BE-28-28E-27.000000E SiT8924BA-22-25E-25.000000E SiT8924BA-12-18E-50.000000E SiT8924BA-23-33E-40.000000E SiT8924BAR72-33E-18.000000E SiT8924BM-12-33N-25.000000E SiT8924BE-23-33E-40.000000E SiT8924BA-72-XXN-20.000000E SiT8924BA-22-33N-25.000000E SiT8924BA-11-33E-20.000000E SiT8924BMB73-33N-25.000000E SiT8924BAL73-33N-8.000000E SiT8924BE-23-33E-16.000000E SiT8924BMB72-33N-25.000000E SiT8924BE-12-33E-48.000000E SiT8924BM-32-18E-25.000000Y SiT8924BE-23-33E-24.000000E SiT8924BAR72-33E-25.000000E SiT8924BA-12-XXE-25.000000E SiT8924BAR12-33E-18.000000E SiT8924BA-12-18N-12.000000E SiT8924BAB12-33E-25.000000E SiT8924BAR12-33E-20.000000E SiT8924BE-73-33E-25.000000E SiT8924BA-13-XXN-14.745600E SiT8924BA-72-25E-25.000000E SiT8924BEB13-28E-27.000000E SiT8924BA-22-25E-50.000000E SiT8924BA-82-33N-4.000000Y SiT8924BE-72-18E-27.000000E SiT8924BE-22-33E-30.000000E SiT8924BA-72-33N-16.000000E SiT8924BE-23-25E-25.000000E SiT8924BA-72-28E-27.000000E SiT8924BEL23-33N-50.000000E SiT8924BAB12-33E-27.000000E SiT8924BE-13-33E-24.576000E SiT8924BA-72-XXE-25.000000E SiT8924BA-73-18E-30.000000E SiT8924BE-12-18E-48.000000E SiT8924BAB32-33E-27.000000Y SiT8924BE-73-33E-27.000000E SiT8924BA-22-33E-3.000000E SiT8924BM-32-33E-40.000000Y SiT8924BA-32-18E-30.000000Y SiT8924BE-12-33N-48.000000E SiT8924BA-72-18E-27.000000E SiT8924BA-72-XXE-26.000000E SiT8924BA-13-33E-50.000000E SiT8924BE-83-33E-66.000000Y SiT8924BA-73-33E-20.000000E SiT8924BA-23-33E-24.576000E SiT8924BE-72-33N-32.000000E SiT8924BA-33-33N-8.000000Y SiT8924BE-13-33E-27.000000E SiT8924BAB72-33E-24.000000E SiT8924BAB12-33E-21.000000E SiT8924BAB12-18E-20.000000E SiT8924BAR72-33E-21.000000E SiT8924BM-12-25E-48.000000E SiT8924BE-33-33E-24.576000Y SiT8924BA-12-18E-25.000000E SiT8924BA-72-18E-25.000000E SiT8924BA-12-33E-30.000000E SiT8924BAR12-33E-25.000000E SiT8924BA-13-18E-19.200000E SiT8924BE-13-33E-16.000000E SiT8924BA-73-XXE-26.000000E SiT8924BAB12-33E-18.000000E SiT8924BA-72-XXE-12.000000E SiT8924BA-72-18E-50.000000E SiT8924BA-18-33N-50.000000E SiT8924BA-82-33N-20.000000Y SiT8924BA-23-33N-50.000000E SiT8924BE-12-33E-25.000000E SiT8924BA-88-33N-27.000000Y SiT8924BA-13-18E-20.000000E SiT8924BA-12-33N-4.000000E SiT8924BA-73-33N-20.000000E